

Taiwan Semiconductor

1A, 400-600V Rectifiers

FEATURES

- Surface mount device type
- Low peakage current
- Compliant to RoHS directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21

APPLICATIONS

• The devices are designed for high frequency miniatures switched Mode power supplies such as adapters, lighting and on-board DC/DC converters.

MECHANICAL DATA

- Case: SOD-123 small outline plastic package
- Molding compound meets UL 94 V-0 flammability rating
- Moisture sensitivity level: level 1, per J-STD-020
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Polarity: Indicated by cathode band
- Weight: 9.5 mg (approximately)

KEY PARAMETERS					
PARAMETER	VALUE	UNIT			
I _{F(AV)}	1	А			
V _{RRM}	400-600	V			
I _{FSM}	7.5	А			
V_F at $I_F=1A$	1.1	V			
T _{J MAX}	150	°C			
Package	SOD-123				
Configuration	Single dice				





PARAMETER	SYMBOL	2CZ4004	2CZ4005	UNIT
Marking code on the device		Z44	Z45	
Non-repetitive peak reverse voltage @I _R =100uA	V _{RRM}	400	600	V
RMS reverse voltage	V _{R(RMS)}	280	420	V
Forward current	lo	1		А
Non-repetitive peak forward surge current 8.3ms half sine wave	I _{FSM}	7.	5	А
Power dissipation	P _D	35	0	mW
Juncion temperature range	TJ	- 55 to	+150	°C
Storage temperature range	T _{STG}	- 55 to	+150	°C

THERMAL PERFORMANCE				
PARAMETER	SYMBOL	LIMIT	UNIT	
Junction-to-ambient thermal resistance	R _{OJA}	357	°C/W	



ELECTRICAL SPECIFICATIONS ($T_A = 25^{\circ}C$ unless otherwise noted)					
PARAMETER	CONDITIONS	SYMBOL	ТҮР	MAX	UNIT
Forward voltage per diode (1)	$I_F = 1A, T_J = 25^{\circ}C$	V _F	-	1.1	V
Reverse current @ rated V _R per	V _R =400V, T _J = 25°C		-	5	μΑ
diode ⁽²⁾	V _R =600V, T _J = 25°C	I _R			
Junction capacitance	1 MHz, V _R =4V	CJ	-	15	pF

Notes:

1. Pulse test with PW=0.3 ms

2. Pulse test with PW=30 ms

ORDERING INFORMATION					
PART NO.(Note. 1)	PACKING CODE	PACKING CODE SUFFIX	PACKAGE	PACKING	
2CZ4004		<u> </u>	000 400		
2CZ4005	RH	G	SOD-123	3K / 7" Reel	

Notes:

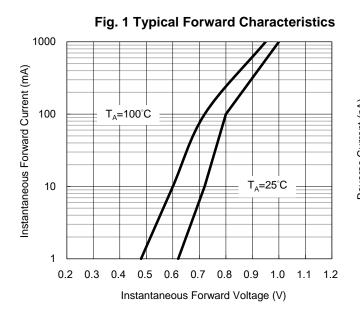
1. Whole series with green compound

EXAMPLE				
EXAMPLE P/N	PART NO.	PACKING CODE	PACKING CODE SUFFIX	DESCRIPTION
2CZ4004 RHG	2CZ4004	RH	G	Green compound



CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$



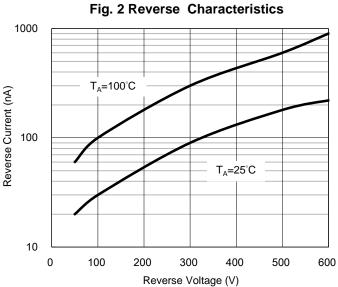
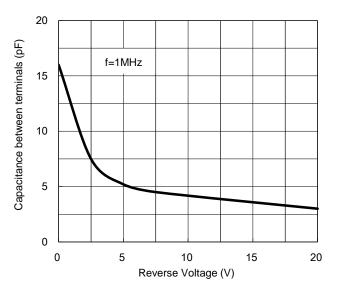


Fig. 3 Capacitance Characteristics

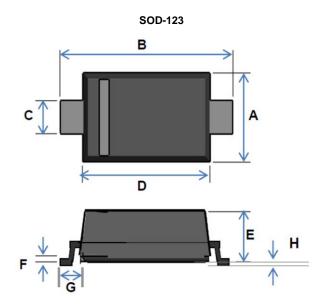




400 (Mu) uoited 200 100 0 25 50 75 100 125 150 Ambient Temperature (°C)

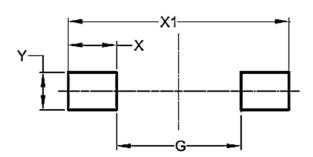


PACKAGE OUTLINE DIMENSION



DIM.	Unit(mm)		Unit(inch)	
DIM.	Min	Max	Min	Max
A	1.40	1.80	0.055	0.071
В	3.55	3.85	0.140	0.152
С	0.45	0.70	0.018	0.028
D	2.55	2.85	0.100	0.112
E	0.95	1.35	0.037	0.053
F	0.05	0.15	0.002	0.006
G	0.50 REF		0.02	REF
н	-	0.10	-	0.004

SUGGEST PAD LAYOUT



DIM.	Unit(mm)	Unit(inch)	
DIN.	Min	Min	
G	2.25	0.089	
Х	0.90	0.035	
X1	4.05	0.159	
Y	0.95	0.037	



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